



get the difference

BADALAC® | ABS 20 GK30

ABS-GB30

Easy-flowing injection molding grade filled with 30% glass beads; intended for thick-walled components with little mold shrinkage

Properties	Test conditions	Test method	Unit	dry as molded
Mechanical Properties				
Tensile Modulus	23°C, 1 mm/Min	ISO 527-1/2	MPa	2800
Tensile Strength at yield	23°C, 50 mm/Min	ISO 527-1/2	MPa	40
Tensile strain at yield	23°C, 50 mm/Min	ISO 527-1/2	%	2.5
Nominal strain at yield	23°C, 50 mm/Min	ISO 527-1/2	%	7
Tensile stress at break	23°C, 5 mm/Min	ISO 527-1/2	MPa	-
Tensile strain at break	23°C, 5 mm/Min	ISO 527-1/2	%	-
Flexural Modulus	23°C	ISO 178	MPa	-
Flexural Strength	23°C	ISO 178	MPa	-
Charpy Impact Strength	23°C -30°C	ISO 179/1eU ISO 179/1eU	kJ/m ² kJ/m ²	30 -
Charpy Notched Impact Strength	23°C -30°C	ISO 179/1eA ISO 179/1eA	kJ/m ² kJ/m ²	8 -
Izod Notched Impact Strength	23°C -30°C	ISO 180/1A ISO 180/1A	kJ/m ² kJ/m ²	- -
Ball indentation hardness	358 N	ISO 2039-1	MPa	-
Thermal Properties				
Melting temperature	10 K/min	ISO 3146	°C	-
Temperature of deflection under load	0,45 MPa 1,8 MPa 8 MPa	ISO 75-1/2 ISO 75-1/2 ISO 75-1/2	°C °C °C	106 101 -
Vicat Softening Temperature	VST A50 VST B50	ISO 306 ISO 306	°C °C	108 98
Coefficient of linear thermal expansion	parallel across	ISO 11359-2 ISO 11359-2	E-4/K E-4/K	- -
Thermal conductivity	Test plate 2 mm	DIN 52612-1	W/(m*K)	-
Maximum service temperature	some hours 20.000 h	IEC-60216 IEC-60216	°C °C	80 -
Flammability		UL94 UL94 UL94 UL94	Wall thickness mm Rating Wall thickness mm Rating	0.8 HB - -
Glow wire test GWIT		IEC-60695-2-13 IEC-60695-2-13 IEC-60695-2-13 IEC-60695-2-13	Wall thickness mm Temperature °C Wall thickness mm Temperature °C	- - - -
Glow wire test GWFI		IEC-60695-2-12 IEC-60695-2-12 IEC-60695-2-12 IEC-60695-2-12	Wall thickness mm Temperature °C Wall thickness mm Temperature °C	- - - -
Electrical Properties				



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Properties	Test conditions	Test method	Unit	dry as molded
Relative Permittivity	1 MHz	IEC-62631-2-1	-	2.8
Dissipation Factor	1 MHz	IEC-62631-2-1	E-4	79
Spec. Volume Resistivity	-	IEC-62631-3-1	Ohm*cm	1.0E13
Spec. Surface Resistivity	-	IEC-62631-3-2	Ohm	1.0E13
Dielectric Strength	-	IEC-60243-1	kV/mm	37
Comparative Tracking Index (CTI)	-	IEC-60112	V	-
Other Data				
Water absorption	23°C, Saturation	ISO 62	%	0.8
Moisture absorption	23°C, 50% r.h.	ISO 62	%	0.18
Density	23°C	ISO 1183	g/cm ³	1.25
Melt Volume Rate (MVR)	Value Temperature Test Load	ISO 1133 ISO 1133 ISO 1133	cm ³ /10min °C kg	- - -
Processing injection molding				
Melt temperature			°C	220 - 260
Mold temperature			°C	30 - 80
Guide Value Moisture			%	< 0.1
Drying temperature			°C	80
Guide Value Drying time			h	2 - 4

Issue date 07.04.2020

Legend

- = not tested
NB = No break

Based on our current state of knowledge, this data represents reference values and, unless otherwise stated, stands for uncoloured material. Therefore, it does not constitute a warranty of certain properties, more particularly it is no material specification. It is the responsibility of the processors to check the suitability of the material for a particular application as well as compliance with statutory regulations and intellectual property rights. The data stated above may be modified at any time without prior notice. The information does not imply any contractual obligation on our part, any liability is expressly excluded.